

# Lead-free Solders in Microelectronics

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Citation Report

#	ARTICLE	IF	CITATIONS
1	Green packages-requirements, materials, results. , 0, , .		7
2	Effect of Cu-containing solders on the critical IMC thickness for the shear strength of BGA solder joints. , 0, , .		6
3	Electromigration of eutectic SnPb and SnAg3.8Cu0.7 flip chip solder bumps and under-bump metallization. Journal of Applied Physics, 2001, 90, 4502-4508.	1.1	218
4	Investigation of UBM systems for electroplated Sn/37Pb and Sn/3.5Ag solder. , 2001, , .		2
5	Influence of Interfacial Reaction on Reliability of QFP Joints with Sn-Ag Based Pb Free Solders. Materials Transactions, 2001, 42, 794-802.	0.4	32
6	Effect of Ag Content on Properties of Sn-Ag Binary Alloy Solder. Materials Transactions, 2001, 42, 286-291.	0.4	37
7	Pb-free solders for flip-chip interconnects. Jom, 2001, 53, 28-33.	0.9	279
8	Effects of microstructural evolution and intermetallic layer growth on shear strength of ball-grid-array Sn-Cu solder joints. Journal of Electronic Materials, 2001, 30, 1323-1331.	1.0	39
9	Experimental determination and thermodynamic calculation of the phase equilibria in the Cu-In-Sn system. Journal of Electronic Materials, 2001, 30, 1093-1103.	1.0	81
10	Surface tension measurements of the Bi-Sn and Sn-Bi-Ag liquid alloys. Journal of Electronic Materials, 2001, 30, 1104-1111.	1.0	69
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12	Stress relaxation behavior of composite and eutectic Sn-Ag solder joints. Journal of Electronic Materials, 2001, 30, 1197-1205.	1.0	51
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16	Reliability of lead free solder joint by using chip size package. , 0, , .		5
17	Reliability issues of Pb-free solder joints in electronic packaging technology. , 0, , .		21
18	Interfacial Microstructure Evolution Between Eutectic SnAgCu Solder and Al/Ni(V)/Cu Thin Films. Journal of Materials Research, 2002, 17, 1612-1621.	1.2	85

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21	Effect of Au addition on Microstructural and Mechanical Properties of Sn-Cu Eutectic Solder. Materials Transactions, 2002, 43, 239-245.	0.4	27
22	Mechanical Properties and Shear Strength of Sn-3.5Ag-Bi Solder Alloys. Materials Transactions, 2002, 43, 1864-1867.	0.4	12
23	Thermodynamic Calculation of Phase Diagram in the Bi-In-Sb Ternary System. Materials Transactions, 2002, 43, 1879-1886.	0.4	29
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38	Correlation between mechanical tensile properties and microstructure of eutectic Sn-3.5Ag solder. <i>Journal of Materials Science Letters</i> , 2002, 21, 723-726.	0.5	35
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1136	Rapid microstructure evolution of structural composite solder joints induced by low-density current stressing. <i>Materials Letters</i> , 2016, 172, 153-156.	1.3	3
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